[0043] On the surface (under surface) of the insulating film **12**, a detection electrode S is provided in the same layer as that of the Y-direction driving electrode **20**Yd. The detection electrode S is formed of comb-shaped electrodes sa and sb, and each electrode ys of the comb-shaped electrodes sa and sb is formed alternately with respect to the Y electrodes y**1**, y**2**, . . . , y**11**, y**12**. In the comb-shaped electrodes sa and sb, the front ends of the combs are formed opposite left to right, the comb-shaped electrodes sa and sb are clustered as one electrode in the center in the Y direction, and these extend up to the predetermined through holes shown in **FIG. 8**.

[0044] In **FIG. 7**, the X electrode layer **20**X is shown as a white-on-black thick line, and in **FIG. 9**, the Y electrode layer **20**Y is shown by a fine solid line. Both electrodes are formed by the electrodes of almost the same width.

[0045] Next, as shown in **FIG. 6, a** flexible insulating film **13** formed of an insulating resin similar to the insulating film **12** is formed by printing on the entire surface including the Y-direction driving electrode **20**Yd.

[0046] As shown in **FIG. 7**, in the input device **1** of this embodiment, end portions Ds of all the electrodes of the X electrode layer **20**X and all the electrodes of the Y electrode layer **20**Y are guided to the end of the extension section **11** formed in the film substrate **10**. On the surface (under surface) of the film substrate **10**, since the protrusion dimension (L**2**) at which the insulating films **12** and **13** overlap the extension section **11** is formed shorter than the protrusion dimension (L**1**+L**2**) of the extension section **11**, when the insulating films **12** and **13** are formed by being multilayered on the film substrate **10**, the end portion Ds of the electrode layer formed on the surface of film substrate **10** is exposed at the surface (see **FIG. 6**). Next, the end portions Ds of the X electrode layer **20**X and the Y electrode layer **20**Y are connected to the conduction section **5** formed in the control circuit substrate **7**. This control circuit substrate **7** is formed at an outer dimension which is sufficiently smaller than that of the film substrate **10**. The portion of the dimension L, which is exposed at this time, is a region connected to the conduction section **5**.

[0047] The control circuit substrate **7** is formed by a substrate **7***a* made of paper phenol, paper epoxy, or glass epoxy, with the conduction section **8** which is connected to the end portion Ds of the electrode layer being formed on one side surface of the substrate **7***a*. In the conduction section **8**, a plurality of lands **8***a* are formed at a predetermined spacing in the X direction. The conduction section **8** can be formed by plating the metal surface of a steel foil or steel with gold or carbon thereon. When resistance and bonding strength are taken into consideration, a conduction section plated with gold is preferably used.

[0048] Since the entirety, excluding the control circuit substrate **7**, of the input sensor **2** formed in this manner is flexible, the input sensor **2** is bonded within a recess **4**C of the support plate **4** in such a manner so as to be arranged along the planar shape of the recess **4**C by means of a double-sided bonding tape (not shown) which is bonded in advance within the recess **4**C on the rear surface, which is formed from the curved section **4**A of the support plate **4** to a planar section **4**B thereof.

[0049] Furthermore, the control circuit substrate **7** connected to the input sensor **2** is bonded on the rear surface of the planar section **4**B of the support plate **4** by means of a double-sided bonding tape (not shown).

[0050] On the other hand, in the front of the surface of the support plate **4**, a pointing section **9** which points the position of the input sensor **2** positioned below the support plate **4** is formed. Therefore, it is possible for an operator to easily know the position of the input sensor supported on the rear surface of the support plate **2**.

[0051] The ease of operation of the pointing section **9** is improved when, as shown in **FIG. 10, a** color display is made on the surface of the housing **4**, surface roughness is varied, or arrows α and β in the scroll direction are displayed in such a manner as to correspond to the rectangular shape of the input sensor **2**.

[0052] As has thus been described, since the input device **1** of this embodiment has the flexible thin input sensor **2**, when the input device **1** is incorporated in the notebook PC **3**, the thickness dimension of the PC **3** can be thinner. Furthermore, since the input device **1** can also be incorporated in the support plate **4**, versatility of incorporation can be increased.

[0053] The planar shape of the control circuit substrate **7** can be made small, and the cost can be reduced.

[0054] Since the support plate **4** is made thinner by forming the recess **4**C, it is possible to stably perform operation of the input device **1** from above the input sensor **2**.

[0055] The present invention is not limited to the above-described embodiments, and various modifications are possible as necessary.

What is claimed is:

1. An electrostatic-capacitance-type coordinate input device comprising an input sensor formed in such a manner that an X electrode layer and a Y electrode layer for detecting electrostatic capacitance are multilayered on a flexible substrate,

wherein said input sensor is bonded on the rear surface of an insulating support plate for supporting said input sensor.

2. An electrostatic-capacitance-type coordinate input device according to claim 1, wherein a recess to which the input sensor is fitted is formed on the rear surface of said support plate at a position where said input sensor is bonded.

3. An electrostatic-capacitance-type coordinate input device according to claim 1, wherein a pointing section for pointing the position of said input sensor is formed in said support plate.

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